

**STD4NS25****N-CHANNEL 250V - 0.9Ω - 4A DPAK/IPAK  
MESH OVERLAY™ MOSFET**

| TYPE     | V <sub>DSS</sub> | R <sub>D(on)</sub> | I <sub>D</sub> |
|----------|------------------|--------------------|----------------|
| STD4NS25 | 250 V            | < 1.1 Ω            | 4 A            |

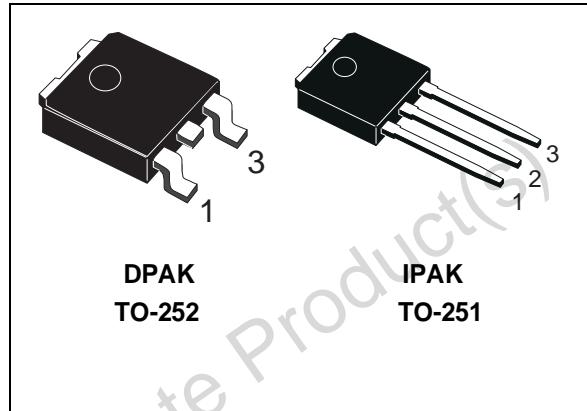
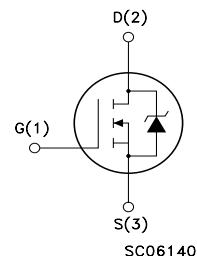
- TYPICAL R<sub>D(on)</sub> = 0.9 Ω
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- ADD SUFFIX "T4" FOR ORDERING IN TAPE & REEL

**DESCRIPTION**

Using the latest high voltage MESH OVERLAY™ process, STMicroelectronics has designed an advanced family of power MOSFETs with outstanding performance. The new patented STrip layout coupled with the Company's proprietary edge termination structure, makes it suitable in converters for lighting applications.

**APPLICATIONS**

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITH MODE POWER SUPPLIES (SMPS)
- DC-DC CONVERTERS FOR TELECOM,  
INDUSTRIAL, AND LIGHTING EQUIPMENT

**INTERNAL SCHEMATIC DIAGRAM****ABSOLUTE MAXIMUM RATINGS**

| Symbol              | Parameter   | Value      | Unit |
|---------------------|---|------------|------|
| V <sub>DS</sub>     | Drain-source Voltage (V <sub>GS</sub> = 0)          | 250        | V    |
| V <sub>DGR</sub>    | Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)        | 250        | V    |
| V <sub>GS</sub>     | Gate- source Voltage                                | ± 20       | V    |
| I <sub>D</sub>      | Drain Current (continuos) at T <sub>C</sub> = 25°C  | 4          | A    |
| I <sub>D</sub>      | Drain Current (continuos) at T <sub>C</sub> = 100°C | 2.5        | A    |
| I <sub>DM</sub> (•) | Drain Current (pulsed)                              | 16         | A    |
| P <sub>TOT</sub>    | Total Dissipation at T <sub>C</sub> = 25°C          | 50         | W    |
|                     | Derating Factor                                     | 0.4        | W/°C |
| dv/dt (1)           | Peak Diode Recovery voltage slope                   | 5          | V/ns |
| T <sub>stg</sub>    | Storage Temperature                                 | -65 to 150 | °C   |
| T <sub>j</sub>      | Max. Operating Junction Temperature                 | 150        | °C   |

(•)Pulse width limited by safe operating area

(1) I<sub>SD</sub>≤ 4A, di/dt≤300 A/μs, V<sub>DD</sub>≤ V<sub>(BR)DSS</sub>, T<sub>j</sub>≤T<sub>jMAX</sub>

## STD4NS25

### THERMAL DATA

|                |  |     |      |
|----------------|--|-----|------|
| Rthj-case      | Thermal Resistance Junction-case Max           | 2.5 | °C/W |
| Rthj-amb       | Thermal Resistance Junction-ambient Max        | 100 | °C/W |
| Rthc-sink      | Thermal Resistance Case-sink Typ               | 1.5 | °C/W |
| T <sub>I</sub> | Maximum Lead Temperature For Soldering Purpose | 275 | °C   |

### AVALANCHE CHARACTERISTICS

| Symbol          | Parameter   | Max Value | Unit |
|-----------------|---|-----------|------|
| I <sub>AR</sub> | Avalanche Current, Repetitive or Not-Repetitive<br>(pulse width limited by T <sub>j</sub> max)                                | 4         | A    |
| E <sub>AS</sub> | Single Pulse Avalanche Energy<br>(starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V) | 120       | mJ   |

### ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

| Symbol               | Parameter   | Test Conditions   | Min. | Typ. | Max.    | Unit     |
|----------------------|---|---|------|------|---------|----------|
| V <sub>(BR)DSS</sub> | Drain-source Breakdown Voltage                        | I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0  | 250  |      |         | V        |
| I <sub>DSS</sub>     | Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0) | V <sub>DS</sub> = Max Rating<br>V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C |      |      | 1<br>10 | μA<br>μA |
| I <sub>GSS</sub>     | Gate-body Leakage Current (V <sub>DS</sub> = 0)       | V <sub>GS</sub> = ±20V  |      |      | ±100    | nA       |

### ON (1)

| Symbol              | Parameter                         | Test Conditions  | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|--|------|------|------|------|
| V <sub>GS(th)</sub> | Gate Threshold Voltage            | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                              | 2    | 3    | 4    | V    |
| R <sub>DS(on)</sub> | Static Drain-source On Resistance | V <sub>GS</sub> = 10V, I <sub>D</sub> = 2 A  |      | 0.9  | 1.1  | Ω    |
| I <sub>D(on)</sub>  | On State Drain Current            | V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>DS(on)max</sub> ,<br>V <sub>GS</sub> = 10V | 4    |      |      | A    |

### DYNAMIC

| Symbol              | Parameter                    | Test Conditions  | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|--|------|------|------|------|
| g <sub>fs</sub> (1) | Forward Transconductance     | V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>DS(on)max</sub> ,<br>I <sub>D</sub> = 2A | 1    | 3.5  |      | S    |
| C <sub>iss</sub>    | Input Capacitance            | V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0                                  |      | 355  |      | pF   |
| C <sub>oss</sub>    | Output Capacitance           |  |      | 64   |      | pF   |
| C <sub>rss</sub>    | Reverse Transfer Capacitance |  |      | 29.5 |      | pF   |

## ELECTRICAL CHARACTERISTICS (CONTINUED)

## SWITCHING ON

| Symbol      | Parameter          | Test Conditions  | Min. | Typ. | Max. | Unit |
|-------------|--------------------|--|------|------|------|------|
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD} = 125\text{ V}$ , $I_D = 2\text{ A}$<br>$R_G = 4.7\Omega$ $V_{GS} = 10\text{ V}$<br>(see test circuit, Figure 3) |      | 12   |      | ns   |
| $t_r$       | Rise Time          |  |      | 18   |      | ns   |
| $Q_g$       | Total Gate Charge  | $V_{DD} = 200\text{V}$ , $I_D = 4\text{ A}$ ,  |      | 19   |      | nC   |
| $Q_{gs}$    | Gate-Source Charge | $V_{GS} = 10\text{V}$  |      | 3.2  |      | nC   |
| $Q_{gd}$    | Gate-Drain Charge  |  |      | 7.5  |      | nC   |

## SWITCHING OFF

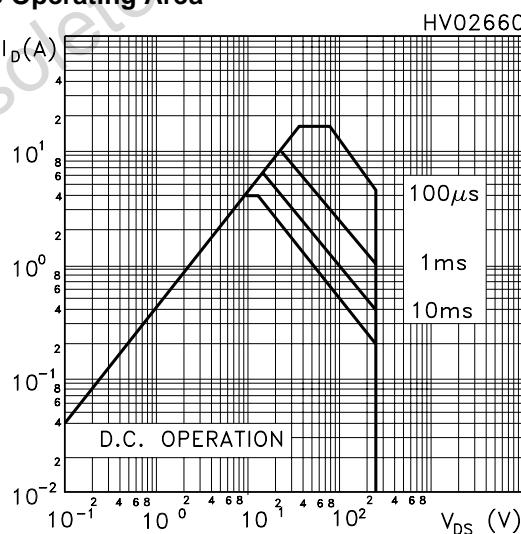
| Symbol                          | Parameter   | Test Conditions   | Min. | Typ.             | Max. | Unit           |
|---------------------------------|---|---|------|------------------|------|----------------|
| $t_{d(Voff)}$<br>$t_f$          | Turn-off- Delay Time<br>Fall Time                     | $V_{DD} = 125\text{V}$ , $I_D = 2\text{ A}$ ,<br>$R_G = 4.7\Omega$ , $V_{GS} = 10\text{V}$<br>(see test circuit, Figure 3)    |      | 70<br>10.5       |      | ns<br>ns       |
| $t_{r(Voff)}$<br>$t_f$<br>$t_c$ | Off-voltage Rise Time<br>Fall Time<br>Cross-over Time | $V_{clamp} = 200\text{V}$ , $I_D = 4\text{ A}$ ,<br>$R_G = 4.7\Omega$ , $V_{GS} = 10\text{V}$<br>(see test circuit, Figure 5) |      | 13<br>10<br>21.5 |      | ns<br>ns<br>ns |

## SOURCE DRAIN DIODE

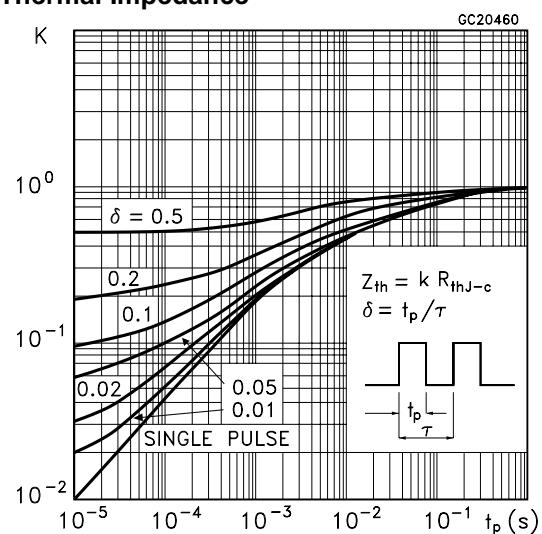
| Symbol                            | Parameter  | Test Conditions  | Min. | Typ.              | Max. | Unit                     |
|-----------------------------------|--|--|------|-------------------|------|--------------------------|
| $I_{SD}$                          | Source-drain Current   |  |      |                   | 4    | A                        |
| $I_{SDM}(2)$                      | Source-drain Current (pulsed)  |  |      |                   | 16   | A                        |
| $V_{SD}(1)$                       | Forward On Voltage   | $I_{SD} = 4\text{ A}$ , $V_{GS} = 0$   |      |                   | 1.5  | V                        |
| $t_{rr}$<br>$Q_{rr}$<br>$I_{RRM}$ | Reverse Recovery Time<br>Reverse Recovery Charge<br>Reverse Recovery Current | $I_{SD} = 4\text{ A}$ , $dI/dt = 100\text{A}/\mu\text{s}$<br>$V_{DD} = 30\text{V}$ , $T_j = 150^\circ\text{C}$<br>(see test circuit, Figure 5) |      | 124<br>0.5<br>7.2 |      | ns<br>$\mu\text{C}$<br>A |

Note: 1. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.  
2. Pulse width limited by safe operating area.

## Safe Operating Area

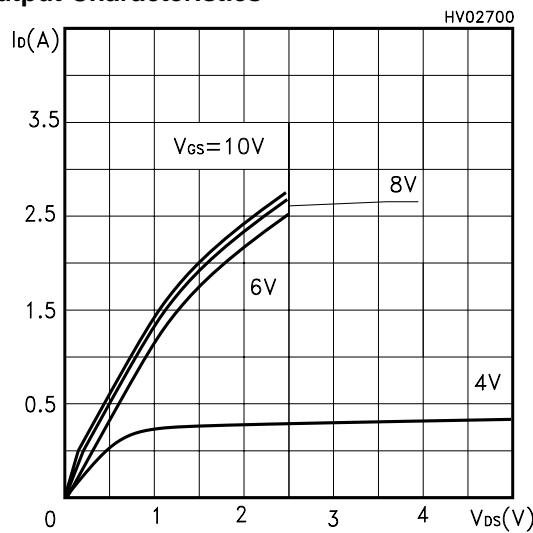


## Thermal Impedance

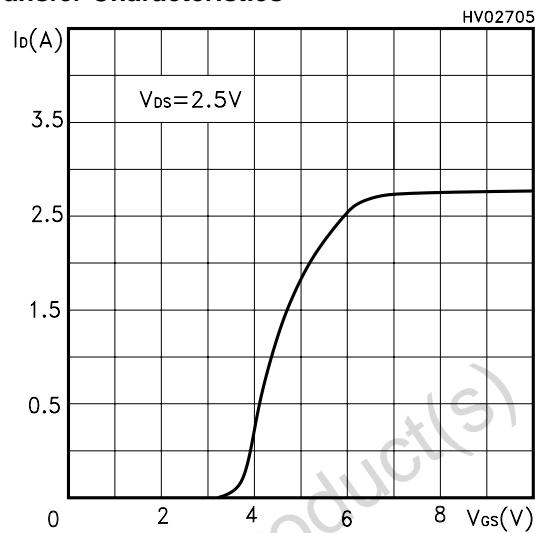


## STD4NS25

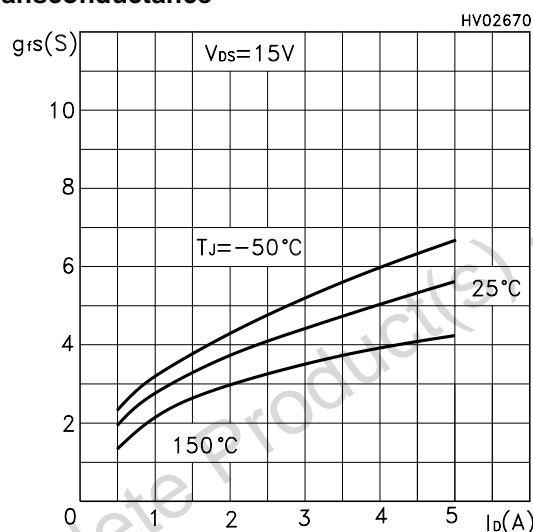
### Output Characteristics



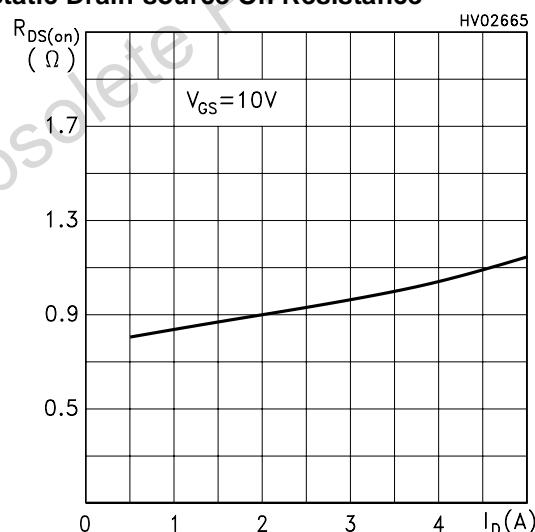
### Transfer Characteristics



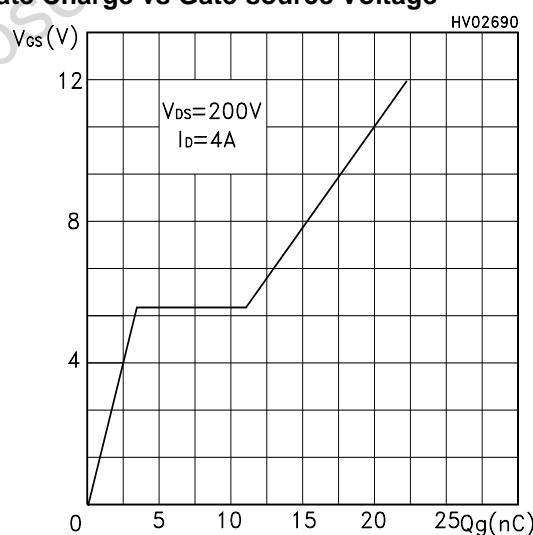
### Transconductance



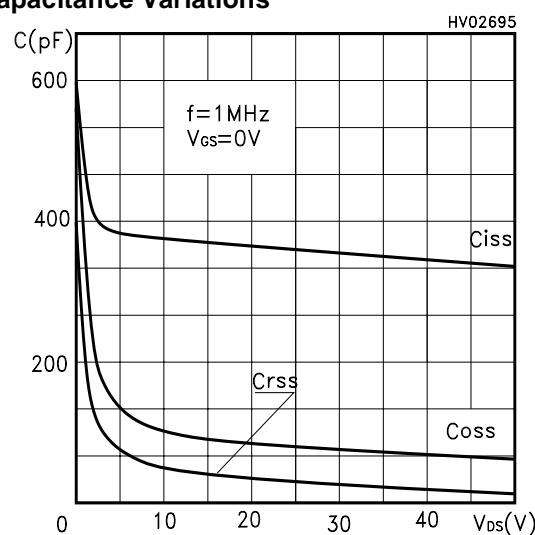
### Static Drain-source On Resistance

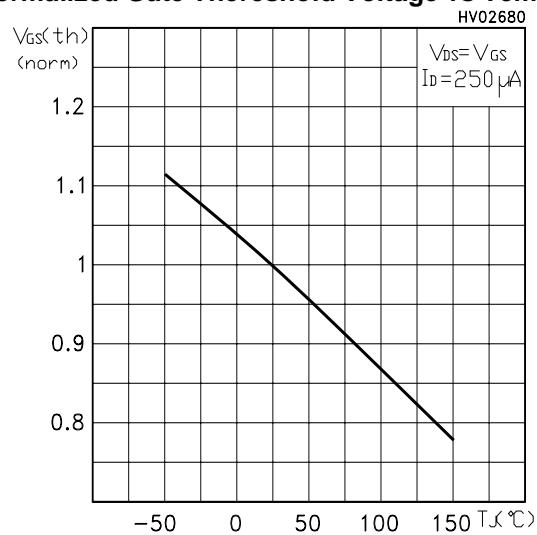
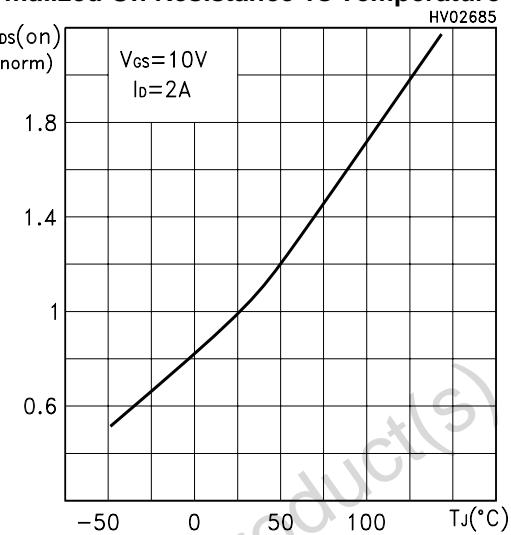
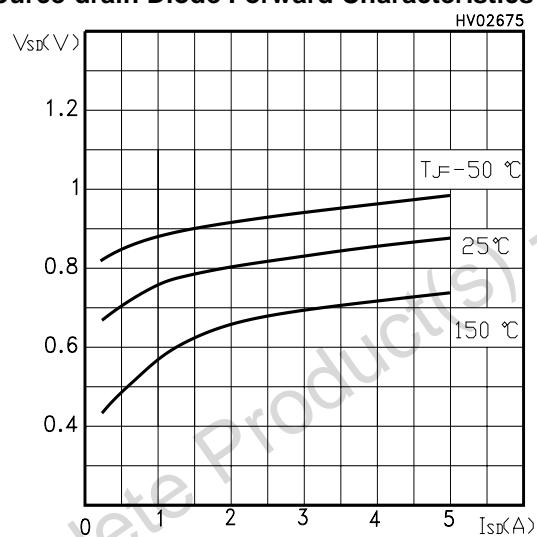


### Gate Charge vs Gate-source Voltage



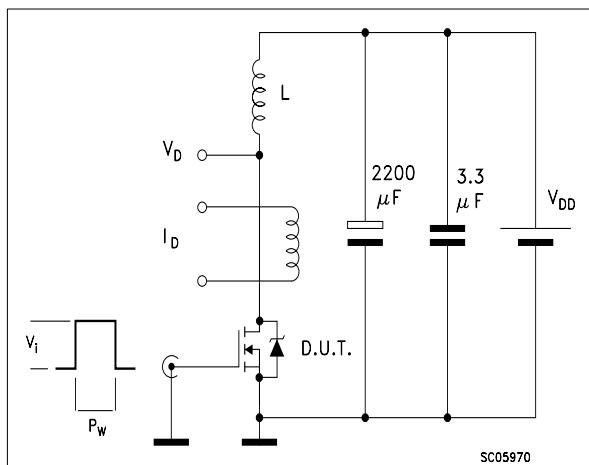
### Capacitance Variations



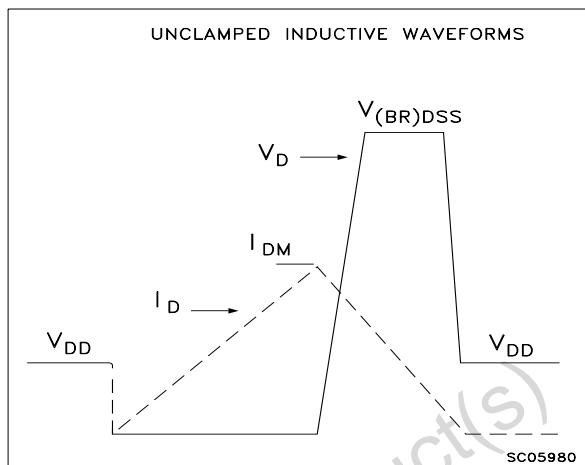
**Normalized Gate Threshold Voltage vs Temp.****Normalized On Resistance vs Temperature****Source-drain Diode Forward Characteristics**

## STD4NS25

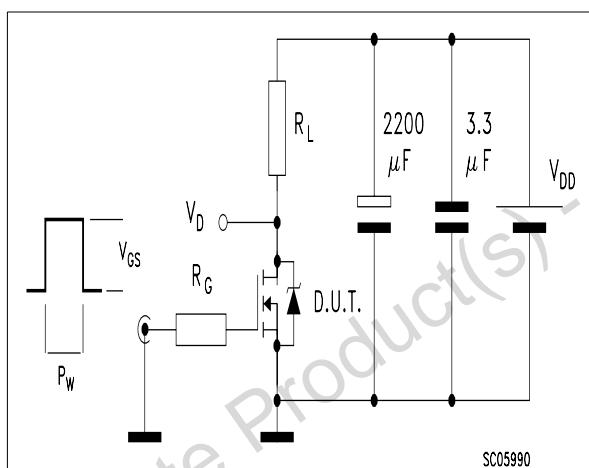
**Fig. 1:** Unclamped Inductive Load Test Circuit



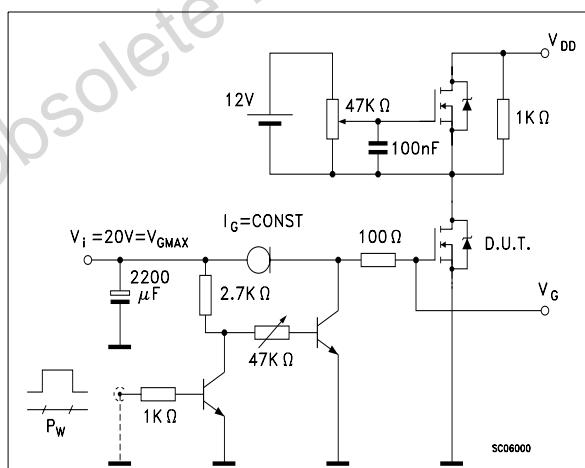
**Fig. 2:** Unclamped Inductive Waveform



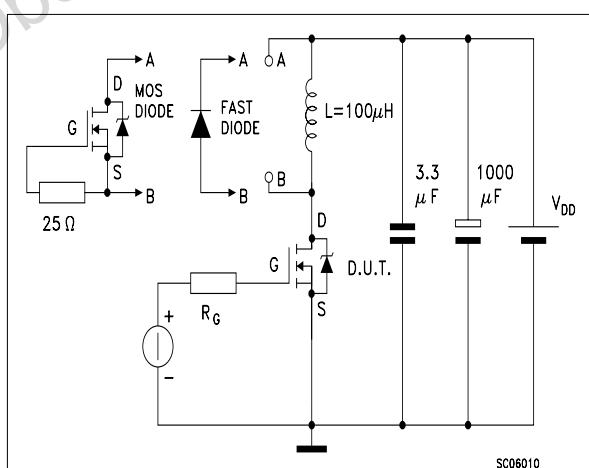
**Fig. 3:** Switching Times Test Circuit For Resistive Load



**Fig. 4:** Gate Charge test Circuit

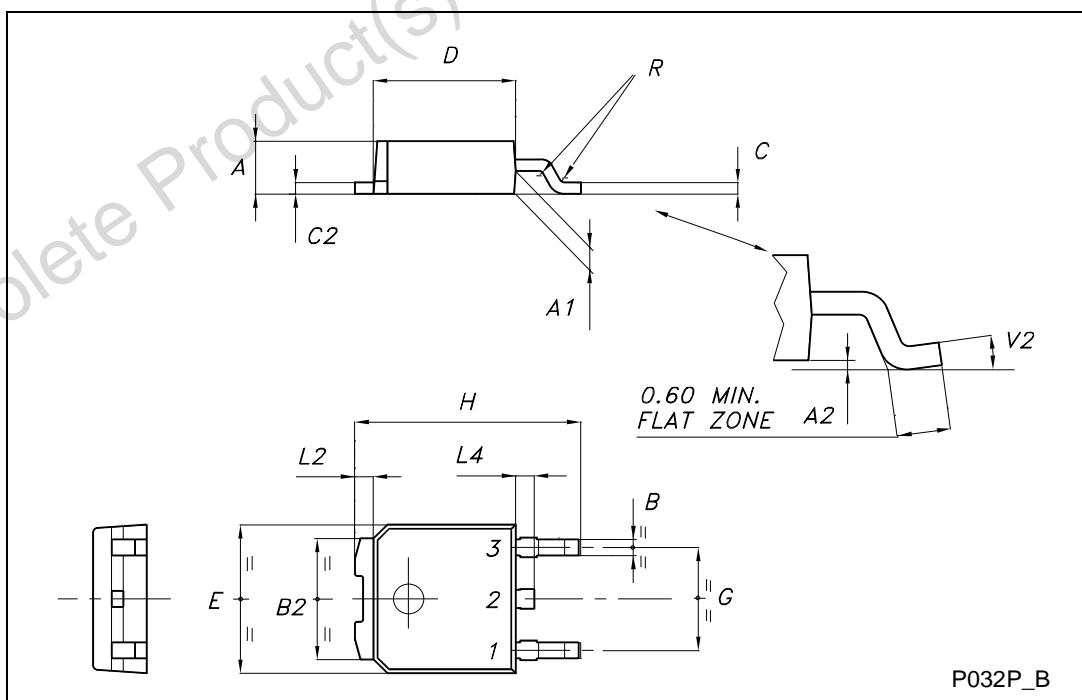


**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



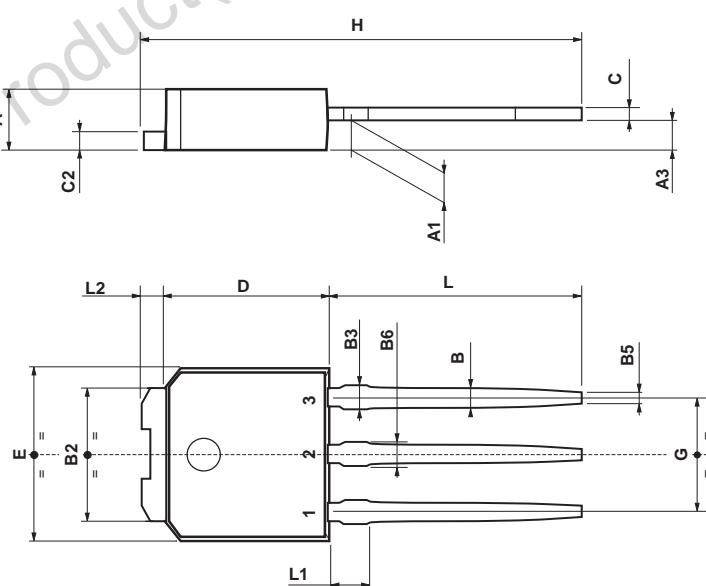
## TO-252 (DPAK) MECHANICAL DATA

| DIM. | mm   |      |       | inch  |       |       |
|------|------|------|-------|-------|-------|-------|
|      | MIN. | TYP. | MAX.  | MIN.  | TYP.  | MAX.  |
| A    | 2.20 |      | 2.40  | 0.087 |       | 0.094 |
| A1   | 0.90 |      | 1.10  | 0.035 |       | 0.043 |
| A2   | 0.03 |      | 0.23  | 0.001 |       | 0.009 |
| B    | 0.64 |      | 0.90  | 0.025 |       | 0.035 |
| B2   | 5.20 |      | 5.40  | 0.204 |       | 0.213 |
| C    | 0.45 |      | 0.60  | 0.018 |       | 0.024 |
| C2   | 0.48 |      | 0.60  | 0.019 |       | 0.024 |
| D    | 6.00 |      | 6.20  | 0.236 |       | 0.244 |
| E    | 6.40 |      | 6.60  | 0.252 |       | 0.260 |
| G    | 4.40 |      | 4.60  | 0.173 |       | 0.181 |
| H    | 9.35 |      | 10.10 | 0.368 |       | 0.398 |
| L2   |      | 0.8  |       |       | 0.031 |       |
| L4   | 0.60 |      | 1.00  | 0.024 |       | 0.039 |
| V2   | 0°   |      | 8°    | 0°    |       | 0°    |



## TO-251 (IPAK) MECHANICAL DATA

| DIM. | mm   |      |      | inch  |       |       |
|------|------|------|------|-------|-------|-------|
|      | MIN. | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    | 2.2  |      | 2.4  | 0.086 |       | 0.094 |
| A1   | 0.9  |      | 1.1  | 0.035 |       | 0.043 |
| A3   | 0.7  |      | 1.3  | 0.027 |       | 0.051 |
| B    | 0.64 |      | 0.9  | 0.025 |       | 0.031 |
| B2   | 5.2  |      | 5.4  | 0.204 |       | 0.212 |
| B3   |      |      | 0.85 |       |       | 0.033 |
| B5   |      | 0.3  |      |       | 0.012 |       |
| B6   |      |      | 0.95 |       |       | 0.037 |
| C    | 0.45 |      | 0.6  | 0.017 |       | 0.023 |
| C2   | 0.48 |      | 0.6  | 0.019 |       | 0.023 |
| D    | 6    |      | 6.2  | 0.236 |       | 0.244 |
| E    | 6.4  |      | 6.6  | 0.252 |       | 0.260 |
| G    | 4.4  |      | 4.6  | 0.173 |       | 0.181 |
| H    | 15.9 |      | 16.3 | 0.626 |       | 0.641 |
| L    | 9    |      | 9.4  | 0.354 |       | 0.370 |
| L1   | 0.8  |      | 1.2  | 0.031 |       | 0.047 |
| L2   |      | 0.8  | 1    |       | 0.031 | 0.039 |



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